

Search Notes

Application No.

10/603,976

Examiner

Stephen W. Smoot

Applicant(s)

JUNG ET AL.

Art Unit

2813

SEARCHED			
Class	Subclass	Date	Examiner
438	637	7/19/2004	SWS
438	675	7/19/2004	SWS
438	684	7/19/2004	SWS
438	692	7/19/2004	SWS
438	693	7/19/2004	SWS
252	79.1	7/19/2004	SWS
252	79.2	7/19/2004	SWS

S.W.S.

SEARCH NOTES (INCLUDING SEARCH STRATEGY)		
	DATE	EXMR
Key Words: CMP - Chemical Mechanical Polishing, Perchloric Acid, Chloric Acid, Hypochlorous Acid,	7/19/2004	S.W.S.
Bromic Acid, Perbromic Acid, Iodic Acid, Periodic Acid, Hard Pad;	7/19/2004	S.W.S.
Wordline - Polysilicon, Nitride Mask, Spacer, Contact Hole, Interlayer - BPSG, FSG, USG, PSG, TEOS.	7/19/2004	S.W.S.
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	7/19/2004	S.W.S.

INTERFERENCE SEARCHED			
Class	Subclass	Date	Examiner